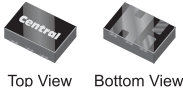


# Material Composition Specification

## TLM621 Case



Device average mass . . . . . **4.5 mg**  
 Fluctuation margin . . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.98%	0.134	Si	7440-21-3	2.98%	0.134	29,777
bond wire	gold	0.37%	0.0167	Au	7440-57-5	0.37%	0.0167	3,711
leadframe	Cu alloy	35.42%	1.594	Cu	7440-50-8	34.22%	1.54	342,215
				Fe	7439-89-6	0.80%	0.036	8,000
				P	7723-14-0	0.01%	0.0004	89
				Zn	7440-66-6	0.04%	0.0017	378
				Ag	7440-22-4	0.36%	0.016	3,555
die attach	silver epoxy	1.49%	0.067	Ag	7440-22-4	1.11%	0.05	11,111
				epoxy resin	Proprietary	0.38%	0.017	3,778
encapsulation*	EMC GREEN	57.14%	2.5713	silica (fused)	60676-86-0	53.62%	2.413	536,210
				epoxy resin	29690-82-2	1.67%	0.075	16,666
				phenol resin	9003-35-4	1.67%	0.075	16,666
				carbon black	1333-86-4	0.18%	0.0083	1,844
plating	matte tin	2.60%	0.117	Sn	7440-31-5	2.60%	0.117	25,999

\*EMC GREEN molding compound is Halogen-Free.

### Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (29-January 2014)